

SMD contact springs are ideal for automatic assembly on printed circuit boards. They are soldered by the standard reflow-soldering process.

The standard basic material used for this SMD contact spring is copper titanium. However, other materials can also be supplied.

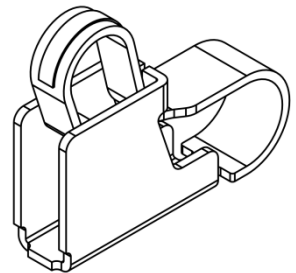
As standard, SMD springs are gold-plated (AU). They can be supplied in a wide range of dimensions and shapes.

- Ideal for automatic assembly
- Standard basic material: YCUT-FX-EH
- Standard plating: AU
- Available in different dimensions and types
- Almost unlimited working life

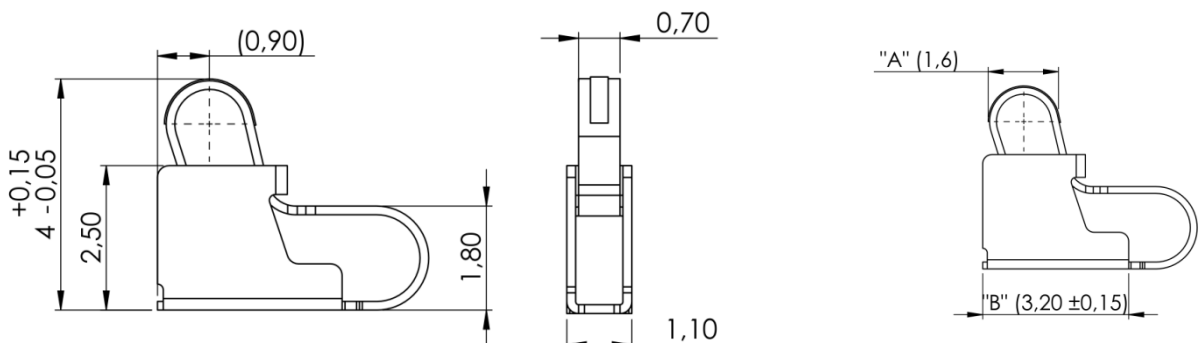


PRODUCT SPECIFICATIONS

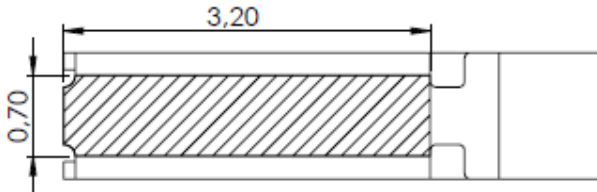
PROPERTY		VALUE / TOLERANCE
Thickness		0,15 mm
Width		1,10 mm ± 0,10
Length		4,70 mm ± 0,10
Height		4,00 mm +0,15/-0,05
Basic material		Copper titanium (YCUT-FX-EH)
Plating	Barrier layer Ni	1,0 µm
	Contact area „A“ AU	0,1 µm
	SMD area „B“ AU	0,05 µm



DIMENSIONS (mm)



RECOMMENDED PAD FOR THE PCB (mm)

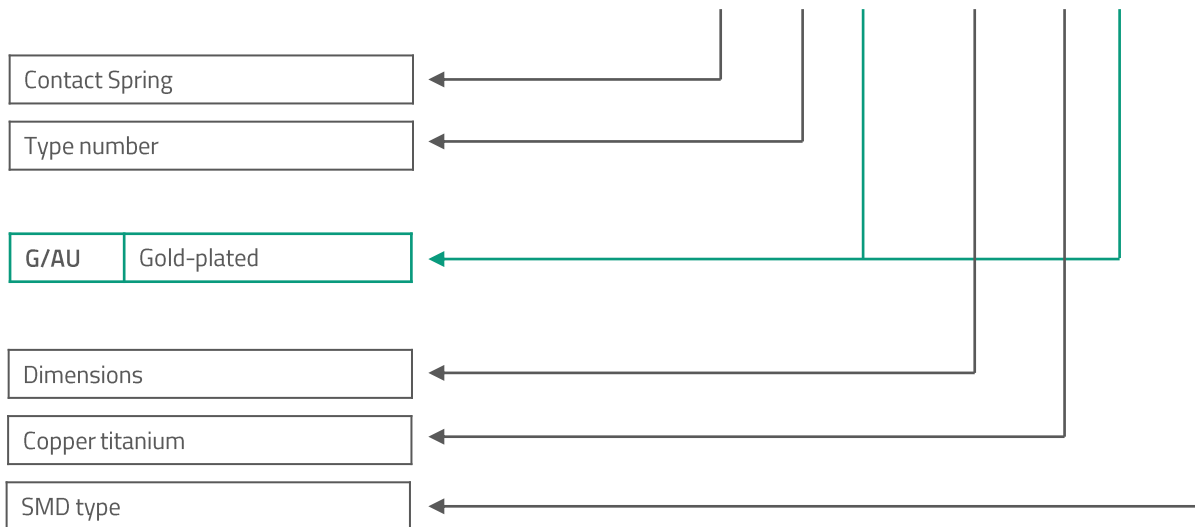


DISCLAIMER

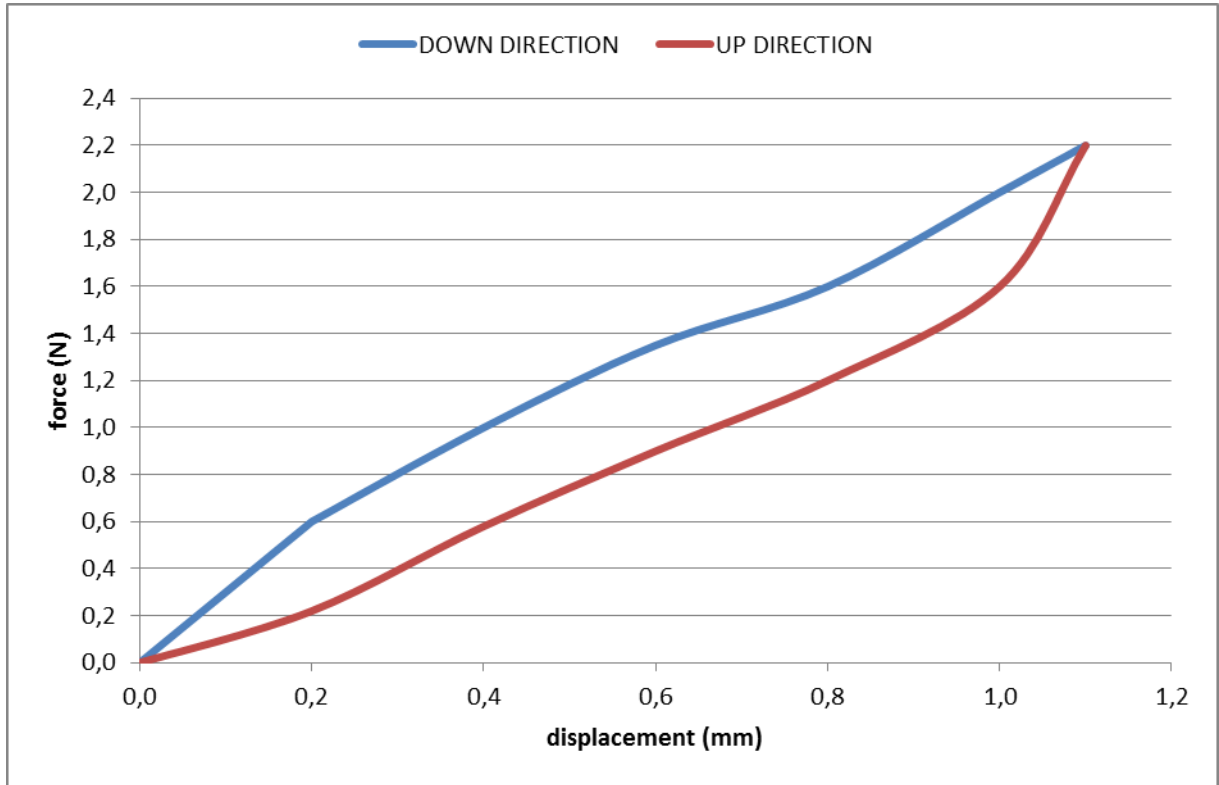
This is only a recommendation based on information available to mtc at the time of printing. Actual land pattern can be significantly different due to various materials and processes used in PCB assembly. mtc makes no representation or warranty of performance based on the recommended land pattern.

BUILDING AN ITEM NUMBER

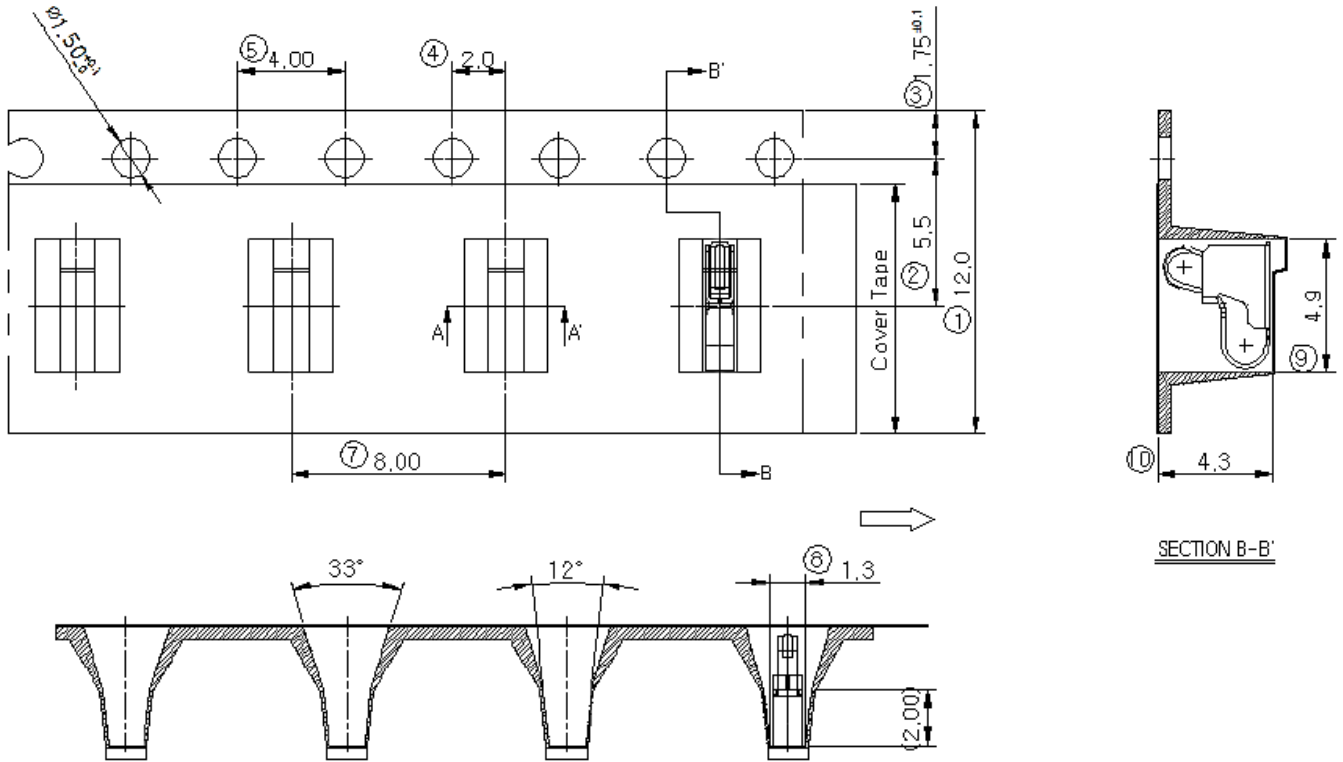
FCB-26YG1147040T-AU-SMD



FORCE DEFLECTION DIAGRAM



PACKING SPECIFICATION – TAPE AND REEL (mm)



- Component packing 330*80*12 mm reel: 1.800 pcs
- Cover Tape: PS. 9,3mm* 480m
- Thickness: 0,3mm ± 0,05

Modifications and errors excepted. The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verifications and testings to determine the suitability for their own particular purpose of any information or products referred to herein.